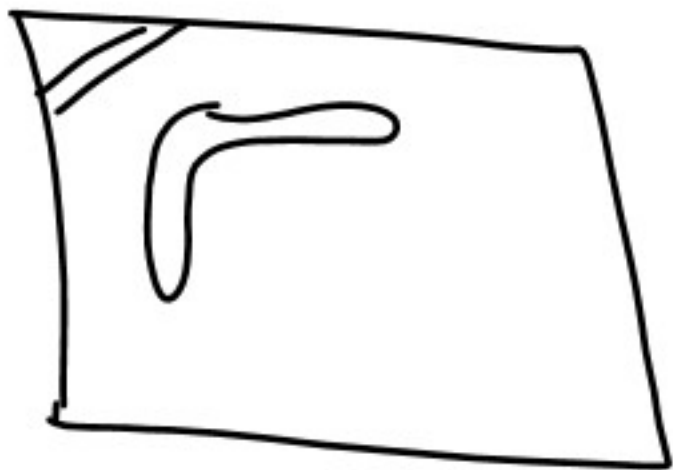
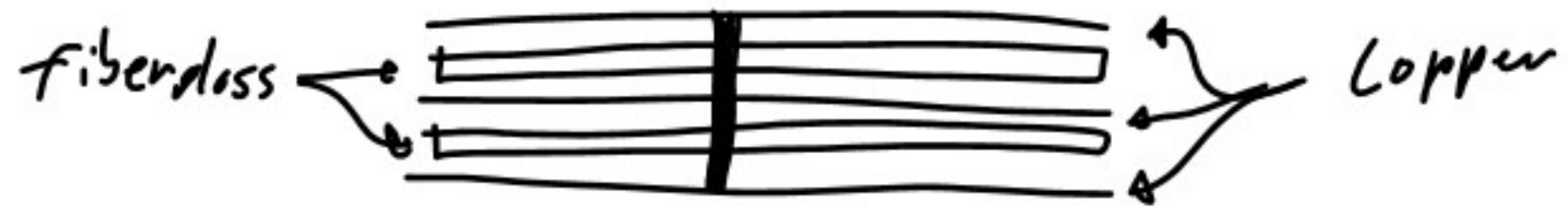


Circuit Board Manufacturing



Etching

Soldermask

Silk screen

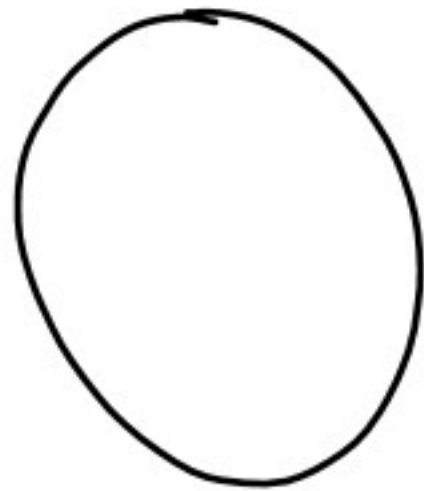
Chip Fabrication

5 nm

2x dia DNA

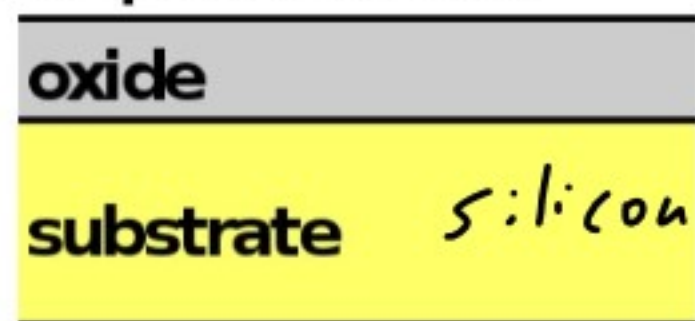
dia hair 80,000 to 100,000 nm

Silicon
Water

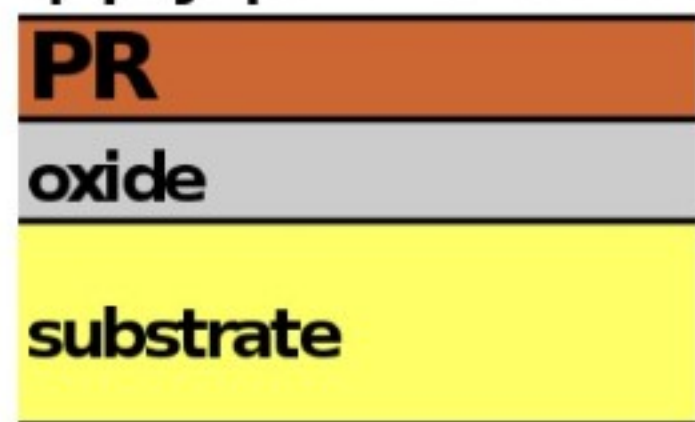


} 00 mm dia

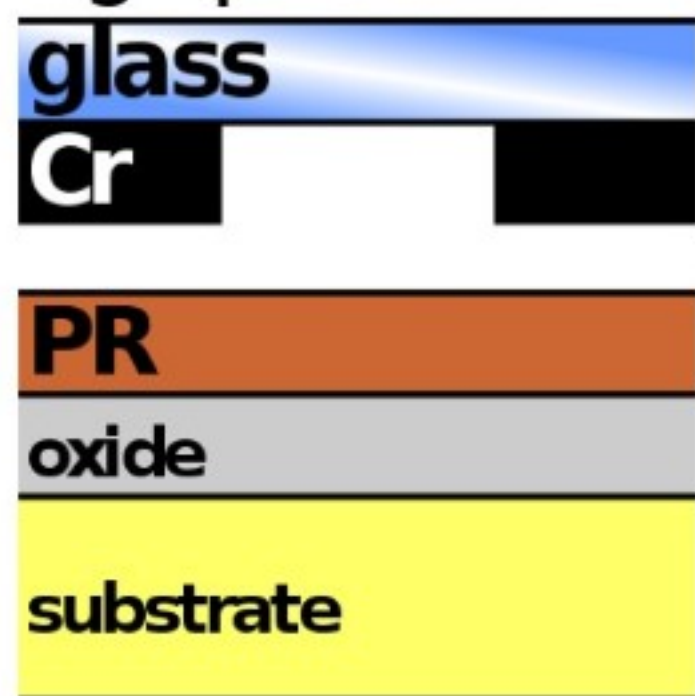
a. Prepare wafer



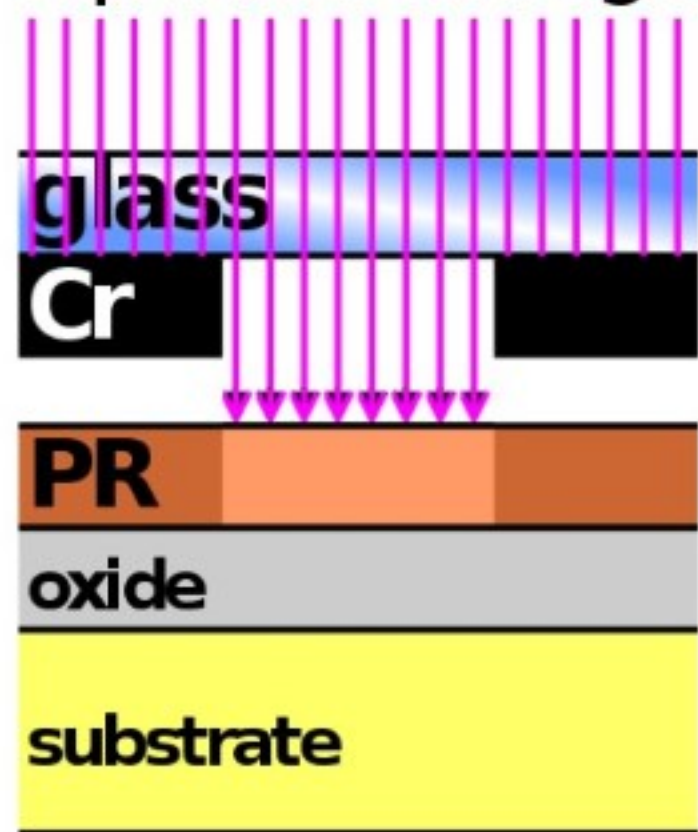
b. Apply photoresist



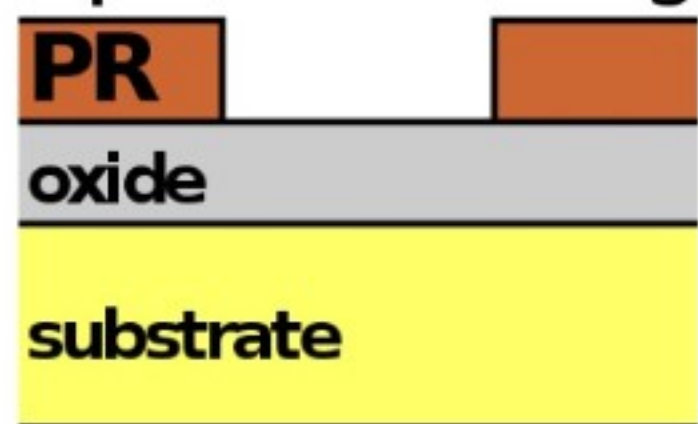
c. Align photomask



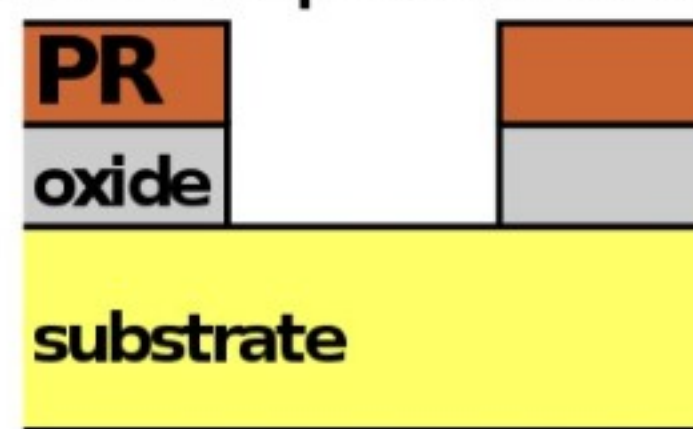
d. Expose to UV light



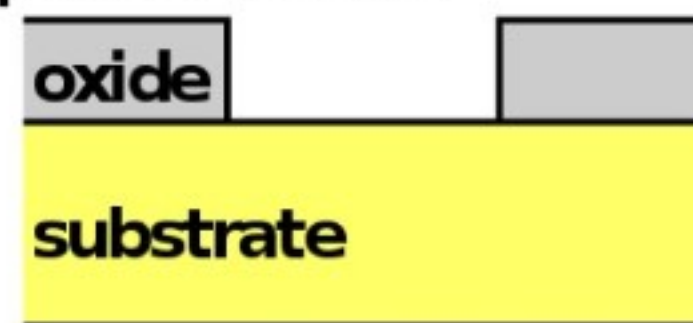
e. Develop and remove photoresist exposed to UV light



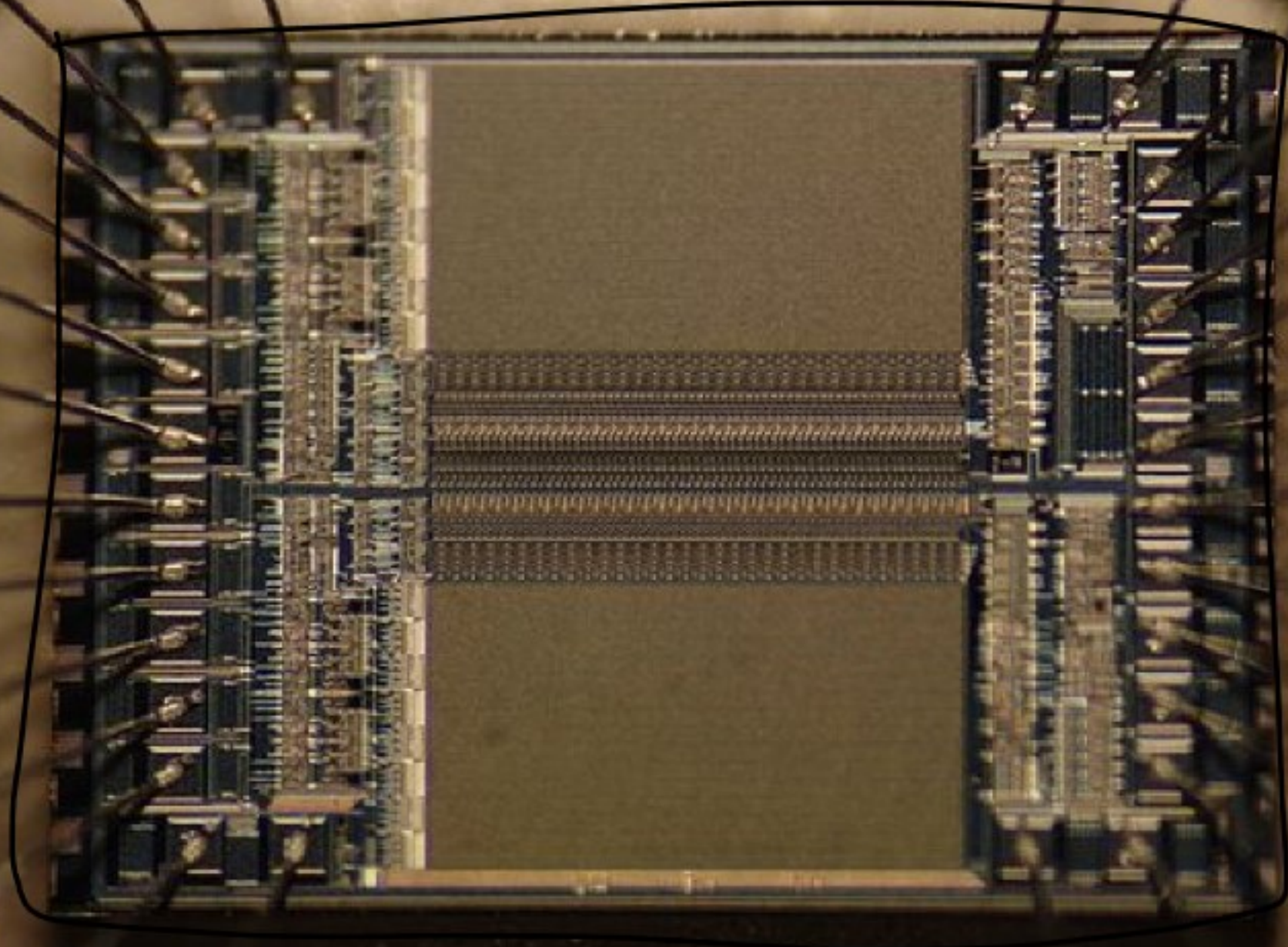
f. Etch exposed oxide

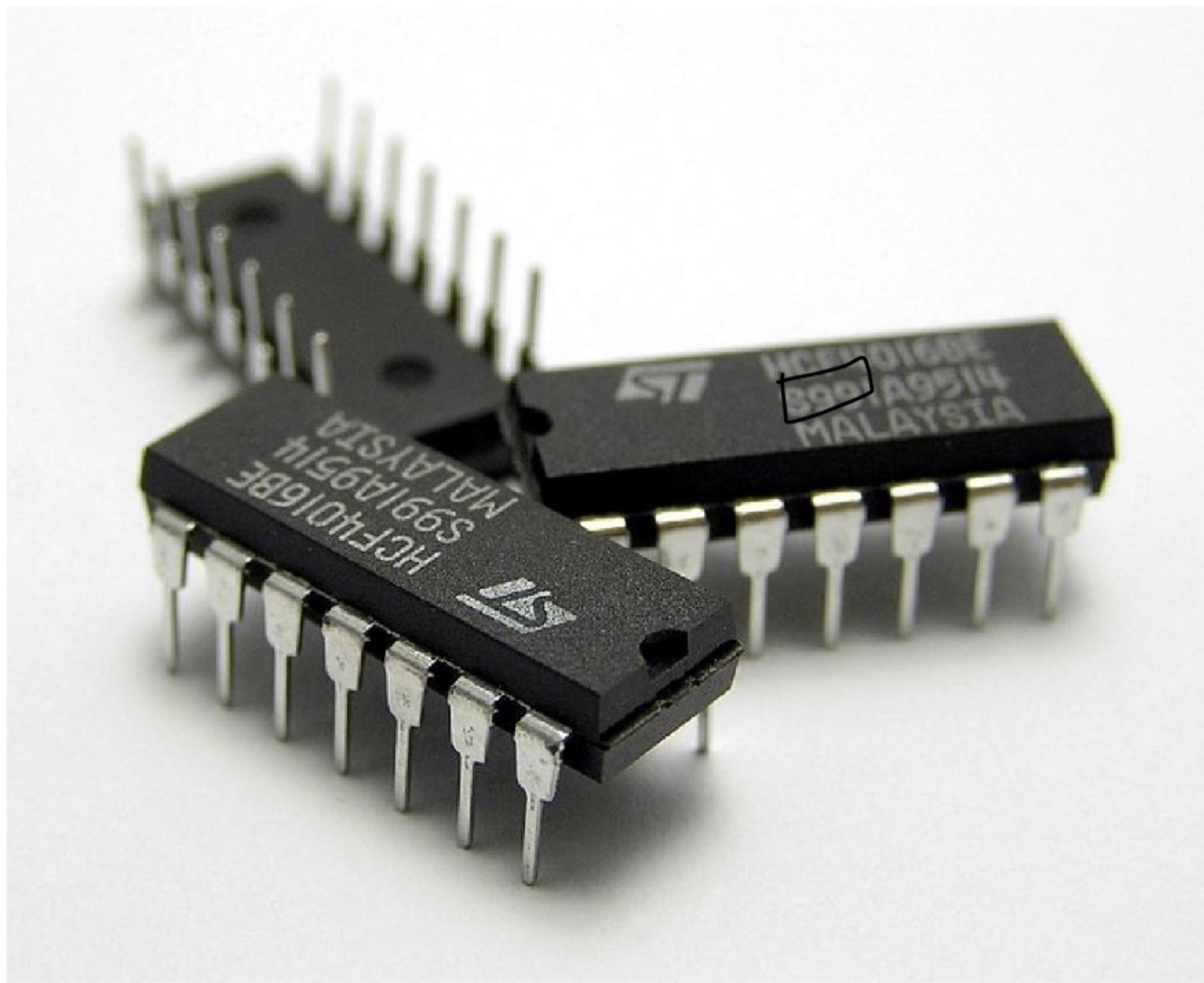


g. Remove remaining photoresist



Die





- ▶ PCB Manufacturing (<https://youtu.be/ljOoGyCso8s>)
- ▶ Chip Fab (<https://youtu.be/2ehSCWoaOqQ>)